Abstracts

Guest Editorial (Sep. 1994, Part II [T-MTT])

D. Maki and V. Tripathi. "Guest Editorial (Sep. 1994, Part II [T-MTT])." 1994 Transactions on Microwave Theory and Techniques 42.9 (Sep. 1994, Part II [T-MTT]): 1725-1726.

With the advancements in MMIC and VLSI technologies, packaging of the resultant high speed digital, and microwave and millimeterwave integrated circuits and systems in a cost effective and high performance manner has become a major challenge. The startling growth of high frequency commercial electronics has brought new demands for increased performance with simultaneous decreases in cost and size on both integrated circuits and packaging and interconnect technologies. Clock rates are increasing, available board space is decreasing and RF operating frequencies are increasing to S and C band for communication components and up to 77 GHz for automotive applications where parasitics can significantly affect performance. This special issue has attempted to present recent advances in packaging for microwave and millimeter wave MMIC's and hybrid circuits and highlight the applications of these microwave oriented techniques to the development of high speed high density digital integrated circuits and modules.

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